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The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	645
Number of Logic Elements/Cells	10320
Total RAM Bits	423936
Number of I/O	179
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce10f17c7n

The chapters in this document, Cyclone IV Device Handbook,, were revised on the following dates. Where chapters or groups of chapters are available separately, part numbers are listed.

- Chapter 1. Cyclone IV FPGA Device Family Overview
Revised: *March 2016*
Part Number: *CYIV-51001-2.0*
- Chapter 2. Logic Elements and Logic Array Blocks in Cyclone IV Devices
Revised: *November 2009*
Part Number: *CYIV-51002-1.0*
- Chapter 3. Memory Blocks in Cyclone IV Devices
Revised: *November 2011*
Part Number: *CYIV-51003-1.1*
- Chapter 4. Embedded Multipliers in Cyclone IV Devices
Revised: *February 2010*
Part Number: *CYIV-51004-1.1*
- Chapter 5. Clock Networks and PLLs in Cyclone IV Devices
Revised: *October 2012*
Part Number: *CYIV-51005-2.4*
- Chapter 6. I/O Features in Cyclone IV Devices
Revised: *March 2016*
Part Number: *CYIV-51006-2.7*
- Chapter 7. External Memory Interfaces in Cyclone IV Devices
Revised: *March 2016*
Part Number: *CYIV-51007-2.6*
- Chapter 8. Configuration and Remote System Upgrades in Cyclone IV Devices
Revised: *May 2013*
Part Number: *CYIV-51008-1.7*
- Chapter 9. SEU Mitigation in Cyclone IV Devices
Revised: *May 2013*
Part Number: *CYIV-51009-1.3*
- Chapter 10. JTAG Boundary-Scan Testing for Cyclone IV Devices
Revised: *December 2013*
Part Number: *CYIV-51010-1.3*
- Chapter 11. Power Requirements for Cyclone IV Devices
Revised: *May 2013*
Part Number: *CYIV-51011-1.3*

Table 1–2 lists Cyclone IV GX device resources.

Table 1–2. Resources for the Cyclone IV GX Device Family

Resources	EP4CGX15	EP4CGX22	EP4CGX30 ⁽¹⁾	EP4CGX30 ⁽²⁾	EP4CGX50 ⁽³⁾	EP4CGX75 ⁽³⁾	EP4CGX110 ⁽³⁾	EP4CGX150 ⁽³⁾
Logic elements (LEs)	14,400	21,280	29,440	29,440	49,888	73,920	109,424	149,760
Embedded memory (Kbits)	540	756	1,080	1,080	2,502	4,158	5,490	6,480
Embedded 18 × 18 multipliers	0	40	80	80	140	198	280	360
General purpose PLLs	1	2	2	4 ⁽⁴⁾	4 ⁽⁴⁾	4 ⁽⁴⁾	4 ⁽⁴⁾	4 ⁽⁴⁾
Multipurpose PLLs	2 ⁽⁵⁾	2 ⁽⁵⁾	2 ⁽⁵⁾	2 ⁽⁵⁾	4 ⁽⁵⁾	4 ⁽⁵⁾	4 ⁽⁵⁾	4 ⁽⁵⁾
Global clock networks	20	20	20	30	30	30	30	30
High-speed transceivers ⁽⁶⁾	2	4	4	4	8	8	8	8
Transceiver maximum data rate (Gbps)	2.5	2.5	2.5	3.125	3.125	3.125	3.125	3.125
PCIe (PIPE) hard IP blocks	1	1	1	1	1	1	1	1
User I/O banks	9 ⁽⁷⁾	9 ⁽⁷⁾	9 ⁽⁷⁾	11 ⁽⁸⁾	11 ⁽⁸⁾	11 ⁽⁸⁾	11 ⁽⁸⁾	11 ⁽⁸⁾
Maximum user I/O ⁽⁹⁾	72	150	150	290	310	310	475	475

Notes to Table 1–2:

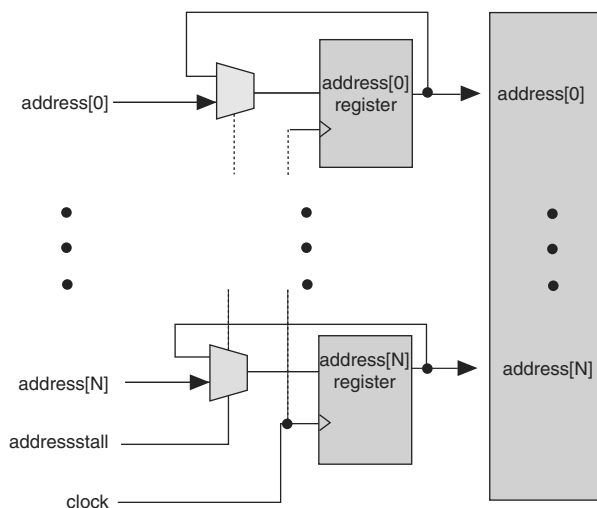
- (1) Applicable for the F169 and F324 packages.
- (2) Applicable for the F484 package.
- (3) Only two multipurpose PLLs for F484 package.
- (4) Two of the general purpose PLLs are able to support transceiver clocking. For more information, refer to the *Clock Networks and PLLs in Cyclone IV Devices* chapter.
- (5) You can use the multipurpose PLLs for general purpose clocking when they are not used to clock the transceivers. For more information, refer to the *Clock Networks and PLLs in Cyclone IV Devices* chapter.
- (6) If PCIe ×1, you can use the remaining transceivers in a quad for other protocols at the same or different data rates.
- (7) Including one configuration I/O bank and two dedicated clock input I/O banks for HSSI reference clock input.
- (8) Including one configuration I/O bank and four dedicated clock input I/O banks for HSSI reference clock input.
- (9) The user I/Os count from pin-out files includes all general purpose I/O, dedicated clock pins, and dual purpose configuration pins. Transceiver pins and dedicated configuration pins are not included in the pin count.

Address Clock Enable Support

Cyclone IV devices M9K memory blocks support an active-low address clock enable, which holds the previous address value for as long as the `addresstall` signal is high (`addresstall = '1'`). When you configure M9K memory blocks in dual-port mode, each port has its own independent address clock enable.

Figure 3–2 shows an address clock enable block diagram. The address register output feeds back to its input using a multiplexer. The multiplexer output is selected by the address clock enable (`addresstall`) signal.

Figure 3–2. Cyclone IV Devices Address Clock Enable Block Diagram



The address clock enable is typically used to improve the effectiveness of cache memory applications during a cache-miss. The default value for the address clock enable signals is low.

Asynchronous Clear

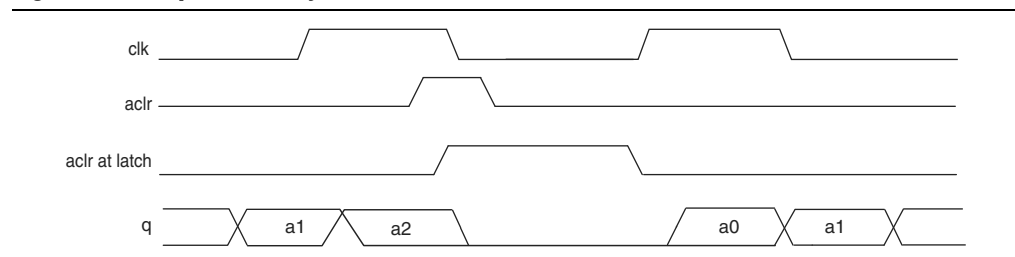
Cyclone IV devices support asynchronous clears for read address registers, output registers, and output latches only. Input registers other than read address registers are not supported. When applied to output registers, the asynchronous clear signal clears the output registers and the effects are immediately seen. If your RAM does not use output registers, you can still clear the RAM outputs using the output latch asynchronous clear feature.



Asserting asynchronous clear to the read address register during a read operation may corrupt the memory content.

Figure 3–5 shows the functional waveform for the asynchronous clear feature.

Figure 3–5. Output Latch Asynchronous Clear Waveform



You can selectively enable asynchronous clears per logical memory using the Quartus II RAM MegaWizard™ Plug-In Manager.



For more information, refer to the *RAM Megafunction User Guide*.

There are three ways to reset registers in the M9K blocks:

- Power up the device
- Use the `aclr` signal for output register only
- Assert the device-wide reset signal using the `DEV_CLRn` option

Memory Modes

Cyclone IV devices M9K memory blocks allow you to implement fully-synchronous SRAM memory in multiple modes of operation. Cyclone IV devices M9K memory blocks do not support asynchronous (unregistered) memory inputs.

M9K memory blocks support the following modes:

- Single-port
- Simple dual-port
- True dual-port
- Shift-register
- ROM
- FIFO

Document Revision History

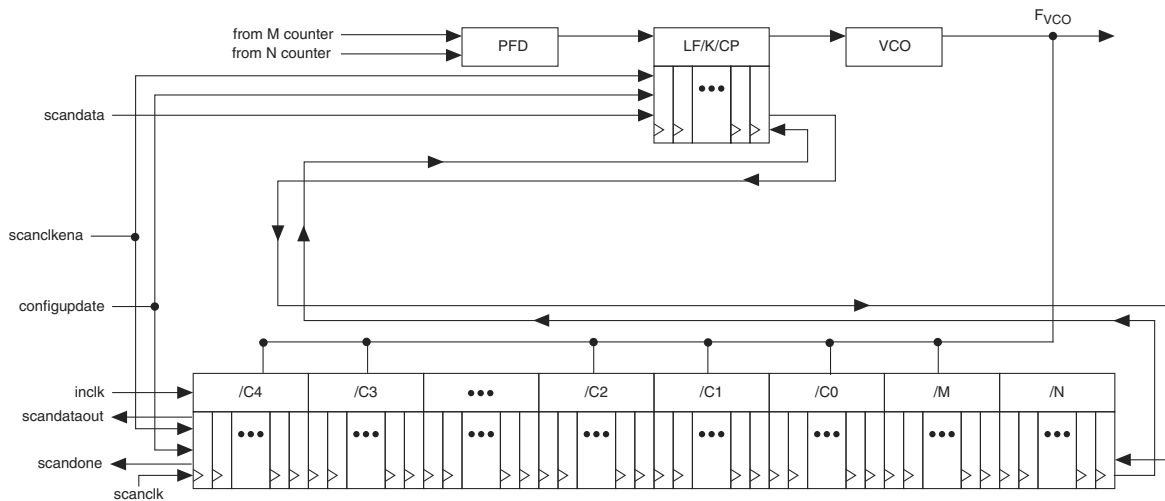
Table 4–3 lists the revision history for this chapter.


Table 4–3. Document Revision History

Date	Version	Changes
February 2010	1.1	Added Cyclone IV E devices in Table 4–1 for the Quartus II software version 9.1 SP1 release.
November 2009	1.0	Initial release.

Figure 5-22 shows how to adjust PLL counter settings dynamically by shifting their new settings into a serial shift register chain or scan chain. Serial data shifts to the scan chain via the `scandata` port, and shift registers are clocked by `scanclk`. The maximum `scanclk` frequency is 100 MHz. After shifting the last bit of data, asserting the `configupdate` signal for at least one `scanclk` clock cycle synchronously updates the PLL configuration bits with the data in the scan registers.

Figure 5-22. PLL Reconfiguration Scan Chain




 The counter settings are updated synchronously to the clock frequency of the individual counters. Therefore, not all counters update simultaneously.

To reconfigure the PLL counters, perform the following steps:


1. The `scanclkena` signal is asserted at least one `scanclk` cycle prior to shifting in the first bit of `scandata` (D0).
2. Serial data (`scandata`) is shifted into the scan chain on the second rising edge of `scanclk`.
3. After all 144 bits have been scanned into the scan chain, the `scanclkena` signal is de-asserted to prevent inadvertent shifting of bits in the scan chain.
4. The `configupdate` signal is asserted for one `scanclk` cycle to update the PLL counters with the contents of the scan chain.
5. The `scandone` signal goes high indicating that the PLL is being reconfigured. A falling edge indicates that the PLL counters have been updated with new settings.
6. Reset the PLL using the `areset` signal if you make any changes to the M, N, post-scale output C counters, or the I_{CP} , R, C settings.
7. You can repeat steps 1 through 5 to reconfigure the PLL any number of times.


Table 6-2 on page 6-7 shows the possible settings for I/O standards with current strength control. These programmable current strength settings are a valuable tool in helping decrease the effects of simultaneously switching outputs (SSO) in conjunction with reducing system noise. The supported settings ensure that the device driver meets the specifications for IOH and IOL of the corresponding I/O standard.

 When you use programmable current strength, on-chip series termination (R_S OCT) is not available.

Slew Rate Control

The output buffer for each Cyclone IV I/O pin provides optional programmable output slew-rate control. Table 6-2 on page 6-7 shows the possible slew rate option and the Quartus II default slew rate setting. However, these fast transitions may introduce noise transients in the system. A slower slew rate reduces system noise, but adds a nominal delay to rising and falling edges. Because each I/O pin has an individual slew-rate control, you can specify the slew rate on a pin-by-pin basis. The slew-rate control affects both the rising and falling edges. Slew rate control is available for single-ended I/O standards with current strength of 8 mA or higher.

 You cannot use the programmable slew rate feature when using OCT with calibration.

 You cannot use the programmable slew rate feature when using the 3.0-V PCI, 3.0-V PCI-X, 3.3-V LVTTTL, or 3.3-V LVCMOS I/O standards. Only the fast slew rate (default) setting is available.


Open-Drain Output

Cyclone IV devices provide an optional open-drain (equivalent to an open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (for example, interrupt and write enable signals) that are asserted by multiple devices in your system.

Bus Hold

Each Cyclone IV device user I/O pin provides an optional bus-hold feature. The bus-hold circuitry holds the signal on an I/O pin at its last-driven state. Because the bus-hold feature holds the last-driven state of the pin until the next input signal is present, an external pull-up or pull-down resistor is not necessary to hold a signal level when the bus is tri-stated.

The bus-hold circuitry also pulls undriven pins away from the input threshold voltage in which noise can cause unintended high-frequency switching. You can select this feature individually for each I/O pin. The bus-hold output drives no higher than V_{CCIO} to prevent overdriving signals.

 If you enable the bus-hold feature, the device cannot use the programmable pull-up option. Disable the bus-hold feature when the I/O pin is configured for differential signals. Bus-hold circuitry is not available on dedicated clock pins.

Bus-hold circuitry is only active after configuration. When going into user mode, the bus-hold circuit captures the value on the pin present at the end of configuration.

The IOE registers in each I/O block share the same source for the preset or clear features. You can program preset or clear for each individual IOE, but you cannot use both features simultaneously. You can also program the registers to power-up high or low after configuration is complete. If programmed to power-up low, an asynchronous clear can control the registers. If programmed to power-up high, an asynchronous preset can control the registers. This feature prevents the inadvertent activation of the active-low input of another device upon power-up. If one register in an IOE uses a preset or clear signal, all registers in the IOE must use that same signal if they require preset or clear. Additionally, a synchronous reset signal is available for the IOE registers.



For more information about the input and output pin delay settings, refer to the *Area and Timing Optimization* chapter in volume 2 of the *Quartus II Handbook*.

PCI-Clamp Diode

Cyclone IV devices provide an optional PCI-clamp diode enabled input and output for each I/O pin. Dual-purpose configuration pins support the diode in user mode if the specific pins are not used as configuration pins for the selected configuration scheme. For example, if you are using the active serial (AS) configuration scheme, you cannot use the clamp diode on the `ASD0` and `nCS0` pins in user mode. Dedicated configuration pins do not support the on-chip diode.

The PCI-clamp diode is available for the following I/O standards:

- 3.3-V LVTTTL
- 3.3-V LVCMOS
- 3.0-V LVTTTL
- 3.0-V LVCMOS
- 2.5-V LVTTTL/LVCMOS
- PCI
- PCI-X

If the input I/O standard is one of the listed standards, the PCI-clamp diode is enabled by default in the Quartus II software.

OCT Support

Cyclone IV devices feature OCT to provide I/O impedance matching and termination capabilities. OCT helps prevent reflections and maintain signal integrity while minimizing the need for external resistors in high pin-count ball grid array (BGA) packages. Cyclone IV devices provide I/O driver on-chip impedance matching and R_S OCT for single-ended outputs and bidirectional pins.



When using R_S OCT, programmable current strength is not available.

There are two ways to implement OCT in Cyclone IV devices:

- OCT with calibration
- OCT without calibration

Table 6–4. Number of VREF Pins Per I/O Bank for Cyclone IV E Devices (Part 2 of 2)

Device	EP4CE6			EP4CE10			EP4CE15						EP4CE22			EP4CE30			EP4CE40				EP4CE55			EP4CE75			EP4CE115	
I/O Bank (1)	144-EQPF	256-UBGA	256-FBGA	144-EQPF	256-UBGA	256-FBGA	144-EQPF	164-MBGA	256-MBGA	256-UBGA	256-FBGA	484-FBGA	144-EQPF	256-UBGA	256-FBGA	324-FBGA	484-FBGA	780-FBGA	324-FBGA	484-UBGA	484-FBGA	780-FBGA	484-UBGA	484-FBGA	780-FBGA	484-UBGA	484-FBGA	780-FBGA	484-FBGA	780-FBGA
8	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3

Note to Table 6–4:

- (1) User I/O pins are used as inputs or outputs; clock input pins are used as inputs only; clock output pins are used as output only.

Table 6–5. Number of VREF Pins Per I/O Bank for Cyclone IV GX Devices

Device	4CGX15	4CGX22		4CGX30			4CGX50		4CGX75		4CGX110			4CGX150		
I/O Bank (1)	169-FBGA	169-FBGA	324-FBGA	169-FBGA	324-FBGA	484-FBGA	484-FBGA	672-FBGA	484-FBGA	672-FBGA	484-FBGA	672-FBGA	896-FBGA	484-FBGA	672-FBGA	896-FBGA
3	1	1		1		3	3		3		3			3		
4	1	1		1		3	3		3		3			3		
5	1	1		1		3	3		3		3			3		
6	1	1		1		3	3		3		3			3		
7	1	1		1		3	3		3		3			3		
8 (2)	1	1		1		3	3		3		3			3		

Notes to Table 6–5:

- (1) User I/O pins are used as inputs or outputs; clock input pins are used as inputs only; clock output pins are used as output only.
 (2) Bank 9 does not have VREF pin. If input pins with VREF I/O standards are used in bank 9 during user mode, it shares the VREF pin in bank 8.

Each Cyclone IV I/O bank has its own VCCIO pins. Each I/O bank can support only one VCCIO setting from among 1.2, 1.5, 1.8, 2.5, 3.0, or 3.3 V. Any number of supported single-ended or differential standards can be simultaneously supported in a single I/O bank, as long as they use the same VCCIO levels for input and output pins.

In Cyclone IV devices, DQS is used only during write mode in DDR2 and DDR SDRAM interfaces. Cyclone IV devices ignore DQS as the read-data strobe because the PHY internally generates the read capture clock for read mode. However, you must connect the DQS pin to the DQS signal in DDR2 and DDR SDRAM interfaces, or to the CQ signal in QDR II SRAM interfaces.



Cyclone IV devices do not support differential strobe pins, which is an optional feature in the DDR2 SDRAM device.



When you use the Altera Memory Controller MegaCore® function, the PHY is instantiated for you. For more information about the memory interface data path, refer to the *External Memory Interface Handbook*.



ALTMEMPHY is a self-calibrating megafunction, enhanced to simplify the implementation of the read-data path in different memory interfaces. The auto-calibration feature of ALTMEMPHY provides ease-of-use by optimizing clock phases and frequencies across process, voltage, and temperature (PVT) variations. You can save on the global clock resources in Cyclone IV devices through the ALTMEMPHY megafunction because you are not required to route the DQS signals on the global clock buses (because DQS is ignored for read capture). Resynchronization issues do not arise because no transfer occurs from the memory domain clock (DQS) to the system domain for capturing data DQ.

All I/O banks in Cyclone IV devices can support DQ and DQS signals with DQ-bus modes of $\times 8$, $\times 9$, $\times 16$, $\times 18$, $\times 32$, and $\times 36$ except Cyclone IV GX devices that do not support left I/O bank interface. DDR2 and DDR SDRAM interfaces use $\times 8$ mode DQS group regardless of the interface width. For a wider interface, you can use multiple $\times 8$ DQ groups to achieve the desired width requirement.

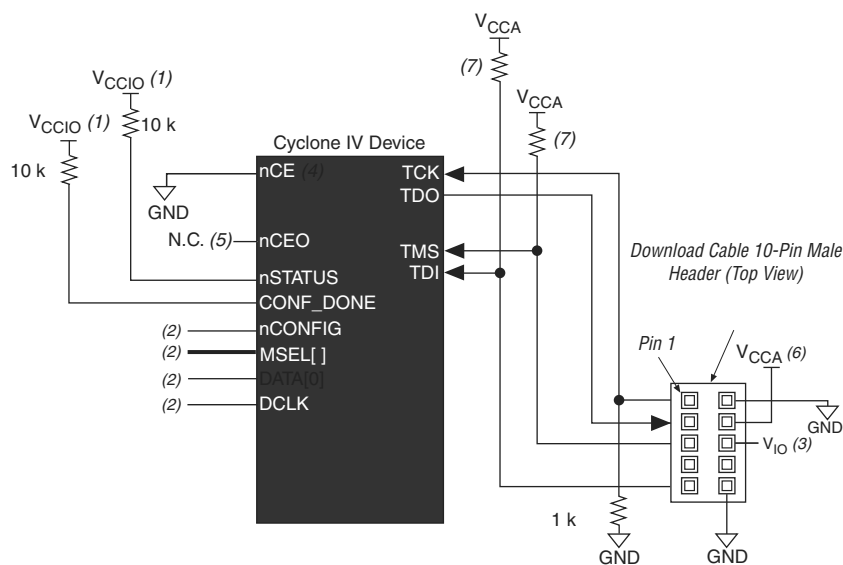
In the $\times 9$, $\times 18$, and $\times 36$ modes, a pair of complementary DQS pins (CQ and CQ#) drives up to 9, 18, or 36 DQ pins, respectively, in the group, to support one, two, or four parity bits and the corresponding data bits. The $\times 9$, $\times 18$, and $\times 36$ modes support the QDR II memory interface. CQ# is the inverted read-clock signal that is connected to the complementary data strobe (DQS or CQ#) pin. You can use any unused DQ pins as regular user I/O pins if they are not used as memory interface signals.



For more information about unsupported DQS and DQ groups of the Cyclone IV transceivers that run at ≥ 2.97 Gbps data rate, refer to the *Cyclone IV Device Family Pin Connection Guidelines*.

For device using V_{CCIO} of 2.5, 3.0, and 3.3 V, refer to Figure 8-23. All I/O inputs must maintain a maximum AC voltage of 4.1 V because JTAG pins do not have the internal PCI clamping diodes to prevent voltage overshoot when using V_{CCIO} of 2.5, 3.0, and 3.3 V. You must power up the V_{CC} of the download cable with a 2.5-V supply from V_{CCA} . For device using V_{CCIO} of 1.2, 1.5, and 1.8 V, refer to Figure 8-24. You can power up the V_{CC} of the download cable with the supply from V_{CCIO} .

Figure 8-23. JTAG Configuration of a Single Device Using a Download Cable (2.5, 3.0, and 3.3-V V_{CCIO} Powering the JTAG Pins)



Notes to Figure 8-23:

- (1) Connect these pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.
- (2) Connect the $nCONFIG$ and $MSEL$ pins to support a non-JTAG configuration scheme. If you only use JTAG configuration, connect the $nCONFIG$ pin to logic-high and the $MSEL$ pins to GND. In addition, pull $DCLK$ and $DATA[0]$ to either high or low, whichever is convenient on your board.
- (3) Pin 6 of the header is a V_{IO} reference voltage for the MasterBlaster output driver. V_{IO} must match the device's V_{CCA} . For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*. When using the USB-Blaster, ByteBlaster II, ByteBlasterMV, and EthernetBlaster cables, this pin is a no connect.
- (4) The nCE pin must be connected to GND or driven low for successful JTAG configuration.
- (5) The $nCEO$ pin is left unconnected or used as a user I/O pin when it does not feed the nCE pin of another device.
- (6) Power up the V_{CC} of the EthernetBlaster, ByteBlaster II, USB-Blaster, or ByteBlasterMV cable with a 2.5-V supply from V_{CCA} . Third-party programmers must switch to 2.5 V. Pin 4 of the header is a V_{CC} power supply for the MasterBlaster cable. The MasterBlaster cable can receive power from either 5.0- or 3.3-V circuit boards, DC power supply, or 5.0 V from the USB cable. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*.
- (7) Resistor value can vary from 1 k Ω to 10 k Ω .

Table 9-7 lists the input and output ports that you must include in the atom.

Table 9-7. CRC Block Input and Output Ports


Port	Input/Output	Definition
<code><crcblock_name></code>	Input	Unique identifier for the CRC block, and represents any identifier name that is legal for the given description language (for example, Verilog HDL, VHDL, and AHDL). This field is required.
<code>.clk (<clock source></code>	Input	This signal designates the clock input of this cell. All operations of this cell are with respect to the rising edge of the clock. Whether it is the loading of the data into the cell or data out of the cell, it always occurs on the rising edge. This port is required.
<code>.shiftnld (<shiftnld source>)</code>	Input	This signal is an input into the error detection block. If <code>shiftnld=1</code> , the data is shifted from the internal shift register to the <code>regout</code> at each rising edge of <code>clk</code> . If <code>shiftnld=0</code> , the shift register parallel loads either the pre-calculated CRC value or the update register contents, depending on the <code>ldsrc</code> port input. To do this, the <code>shiftnld</code> must be driven low for at least two clock cycles. This port is required.
<code>.ldsrc (<ldsrc source>)</code>	Input	This signal is an input into the error detection block. If <code>ldsrc=0</code> , the pre-computed CRC register is selected for loading into the 32-bit shift register at the rising edge of <code>clk</code> when <code>shiftnld=0</code> . If <code>ldsrc=1</code> , the signature register (result of the CRC calculation) is selected for loading into the shift register at the rising edge of <code>clk</code> when <code>shiftnld=0</code> . This port is ignored when <code>shiftnld=1</code> . This port is required.
<code>.crcerror (<crcerror indicator output>)</code>	Output	This signal is the output of the cell that is synchronized to the internal oscillator of the device (80-MHz internal oscillator) and not to the <code>clk</code> port. It asserts high if the error block detects that a SRAM bit has flipped and the internal CRC computation has shown a difference with respect to the pre-computed value. You must connect this signal either to an output pin or a bidirectional pin. If it is connected to an output pin, you can only monitor the <code>CRC_ERROR</code> pin (the core cannot access this output). If the <code>CRC_ERROR</code> signal is used by core logic to read error detection logic, you must connect this signal to a <code>BIDIR</code> pin. The signal is fed to the core indirectly by feeding a <code>BIDIR</code> pin that has its output enable port connected to V_{CC} (see Figure 9-3 on page 9-8).
<code>.regout (<registered output>)</code>	Output	This signal is the output of the error detection shift register synchronized to the <code>clk</code> port to be read by core logic. It shifts one bit at each cycle, so you should clock the <code>clk</code> signal 31 cycles to read out the 32 bits of the shift register.

Recovering from CRC Errors

The system that the Altera FPGA resides in must control device reconfiguration. After detecting an error on the `CRC_ERROR` pin, strobing the `nCONFIG` low directs the system to perform the reconfiguration at a time when it is safe for the system to reconfigure the FPGA.


When the data bit is rewritten with the correct value by reconfiguring the device, the device functions correctly.

While soft errors are uncommon in Altera devices, certain high-reliability applications might require a design to account for these errors.

 The user I/O pins and dual-purpose I/O pins have weak pull-up resistors, which are always enabled (after POR) before and during configuration. The weak pull up resistors are not enabled prior to POR.


A possible concern for semiconductor devices in general regarding hot socketing is the potential for latch up. Latch up can occur when electrical subsystems are hot socketed into an active system. During hot socketing, the signal pins may be connected and driven by the active system before the power supply can provide current to the V_{CC} of the device and ground planes. This condition can lead to latch up and cause a low-impedance path from V_{CC} to GND in the device. As a result, the device extends a large amount of current, possibly causing electrical damage.

The design of the I/O buffers and hot-socketing circuitry ensures that Cyclone IV devices are immune to latch up during hot-socketing.

 For more information about the hot-socketing specification, refer to the *Cyclone IV Device Datasheet* chapter and the *Hot-Socketing and Power-Sequencing Feature and Testing for Altera Devices* white paper.

Hot-socketing Feature Implementation

The hot-socketing circuit does not include the `CONF_DONE`, `nCEO`, and `nSTATUS` pins to ensure that they are able to operate during configuration. The expected behavior for these pins is to drive out during power-up and power-down sequences.

 Altera uses GND as reference for hot-socketing operation and I/O buffer designs. To ensure proper operation, Altera recommends connecting the GND between boards before connecting the power supplies. This prevents the GND on your board from being pulled up inadvertently by a path to power through other components on your board. A pulled up GND can otherwise cause an out-of-specification I/O voltage or current condition with the Altera device.

Power-On Reset Circuitry

Cyclone IV devices contain POR circuitry to keep the device in a reset state until the power supply voltage levels have stabilized during power up. During POR, all user I/O pins are tri-stated until the power supplies reach the recommended operating levels. In addition, the POR circuitry also ensures the V_{CCIO} level of I/O banks that contain configuration pins reach an acceptable level before configuration is triggered.

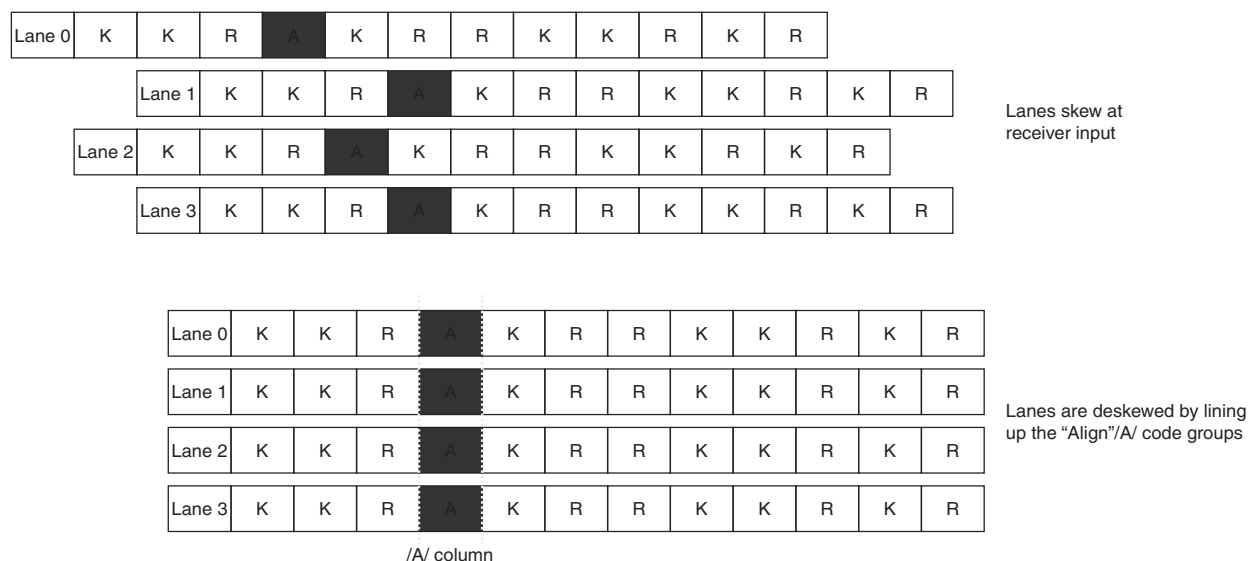
The POR circuit of the Cyclone IV device monitors the V_{CCINT} , V_{CCA} , and V_{CCIO} that contain configuration pins during power-on. You can power up or power down the V_{CCINT} , V_{CCA} , and V_{CCIO} pins in any sequence. The V_{CCINT} , V_{CCA} , and V_{CCIO} must have a monotonic rise to their steady state levels. All V_{CCA} pins must be powered to 2.5V (even when PLLs are not used), and must be powered up and powered down at the same time.

After the Cyclone IV device enters the user mode, the POR circuit continues to monitor the V_{CCINT} and V_{CCA} pins so that a brown-out condition during user mode is detected. If the V_{CCINT} or V_{CCA} voltage sags below the POR trip point during user mode, the POR circuit resets the device. If the V_{CCIO} voltage sags during user mode, the POR circuit does not reset the device.

- Channel alignment is acquired if three additional aligned `||A||` columns are observed at the output of the deskew FIFOs of the four channels after alignment of the first `||A||` column.
- Channel alignment is indicated by the assertion of `rx_channelaligned` signal.
- After acquiring channel alignment, if four misaligned `||A||` columns are seen at the output of the deskew FIFOs in all four channels with no aligned `||A||` columns in between, the `rx_channelaligned` signal is deasserted, indicating loss of channel alignment.

Figure 1-65 shows lane skew at the receiver input and how the deskew FIFO uses the `/A/` code group to align the channels.

Figure 1-65. Deskew FIFO—Lane Skew at the Receiver Input



Lane Synchronization

In XAUI mode, the word aligner is configured in automatic synchronization state machine mode that is compliant to the PCS synchronization state diagram specified in clause 48 of the IEEE P802.3ae specification. Table 1-23 lists the synchronization state machine parameters that implements the lane synchronization in XAUI mode.

Table 1-23. Synchronization State Machine Parameters ⁽¹⁾

Parameter	Value
Number of valid synchronization (<code>/K28.5/</code>) code groups received to achieve synchronization	4
Number of erroneous code groups received to lose synchronization	4
Number of continuous good code groups received to reduce the error count by one	4

Note to Table 1-23:

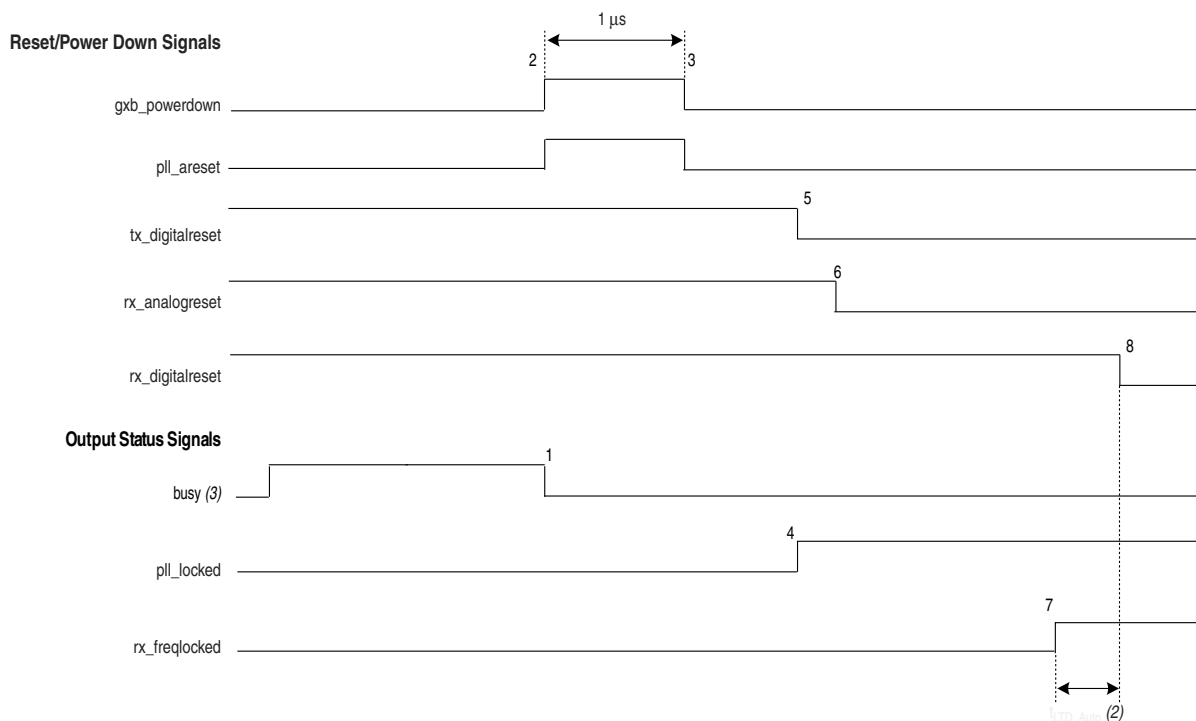
(1) The word aligner supports 7-bit and 10-bit pattern lengths in XAUI mode.

Table 1–28. PIPE Interface Ports in ALTGX Megafunction for Cyclone IV GX⁽¹⁾ (Part 1 of 2)

Port Name	Input/ Output	Clock Domain	Description
fixedclk	Input	Clock signal	125-MHz clock for receiver detect and offset cancellation only in PIPE mode.
tx_detectrxloop	Input	Asynchronous signal	Receiver detect or reverse parallel loopback control. <ul style="list-style-type: none"> ■ A high level in the P1 power state and <code>tx_forceelecidle</code> signal asserted begins the receiver detection operation to determine if there is a valid receiver downstream. This signal must be deasserted when the <code>pipephydonestatus</code> signal indicates receiver detect completion. ■ A high level in the P0 power state with the <code>tx_forceelecidle</code> signal deasserted dynamically configures the channel to support reverse parallel loopback mode.
tx_forcedisp compliance	Input	Asynchronous signal	Force the 8B/10B encoder to encode with negative running disparity. <ul style="list-style-type: none"> ■ Assert only when transmitting the first byte of the PIPE-compliance pattern to force the 8B/10B encoder with a negative running disparity.
pipe8b10binvpolarity	Input	Asynchronous signal	Invert the polarity of every bit of the 10-bit input to the 8B/10B decoder
powerdn	Input	Asynchronous signal	PIPE power state control. <ul style="list-style-type: none"> ■ Signal is 2 bits wide and is encoded as follows: <ul style="list-style-type: none"> ■ 2'b00: P0 (Normal operation) ■ 2'b01: P0s (Low recovery time latency, low power state) ■ 2'b10: P1 (Longer recovery time latency, lower power state) ■ 2'b11: P2 (Lowest power state)
pipedatavalid	Output	N/A	Valid data and control on the <code>rx_dataout</code> and <code>rx_ctrlldetect</code> ports indicator.
pipephydone status	Output	Asynchronous signal	PHY function completion indicator. <ul style="list-style-type: none"> ■ Asserted for one clock cycle to communicate completion of several PHY functions, such as power state transition and receiver detection.
pipeelecidle	Output	Asynchronous signal	Electrical idle detected or inferred at the receiver indicator. <ul style="list-style-type: none"> ■ When electrical idle inference is used, this signal is driven high when it infers an electrical idle condition ■ When electrical idle inference is not used, the <code>rx_signaldetect</code> signal is inverted and driven on this port.

The deassertion of the busy signal indicates proper completion of the offset cancellation process on the receiver channel.

Figure 2–13. Sample Reset Sequence of a Receiver and Transmitter Channels-Receiver CDR in Automatic Lock Mode with the Optional gxb_powerdown Signal ⁽¹⁾



Notes to Figure 2–13:

- (1) The gxb_powerdown signal must not be asserted during the offset cancellation sequence.
- (2) For t_{LTD_Auto} duration, refer to the *Cyclone IV Device Datasheet* chapter.
- (3) The busy signal is asserted and deasserted only during initial power up when offset cancellation occurs. In subsequent reset sequences, the busy signal is asserted and deasserted only if there is a read or write operation to the ALTGX_RECONFIG megafunction.

Simulation Requirements

The following are simulation requirements:

- The gxb_powerdown port is optional. In simulation, if the gxb_powerdown port is not instantiated, you must assert the tx_digitalreset, rx_digitalreset, and rx_analogreset signals appropriately for correct simulation behavior.
- If the gxb_powerdown port is instantiated, and the other reset signals are not used, you must assert the gxb_powerdown signal for at least 1 μ s for correct simulation behavior.
- You can deassert the rx_digitalreset signal immediately after the rx_freqlocked signal goes high to reduce the simulation run time. It is not necessary to wait for t_{LTD_Auto} (as suggested in the actual reset sequence).
- The busy signal is deasserted after about 20 parallel reconfig_clk clock cycles in order to reduce simulation run time. For silicon behavior in hardware, you can follow the reset sequences described in the previous pages.

Method 3: Writing Different Control Signals for all the Transceiver Channels at the Same Time

If you disable the **Use the same control signal for all the channels** option, the PMA control ports for a write transaction are separate for each channel. If you disable this option, the width of the PMA control ports are fixed as follows:

PMA Control Ports Used in a Write Transaction

- `tx_vodctrl` is 3 bits per channel
- `tx_preemp` are 5 bits per channel
- `rx_eqdcgain` is 2 bits per channel
- `rx_eqctrl` is 4 bits per channel

For example, if you have two channels, the `tx_vodctrl` is 6 bits wide (`tx_vodctrl [2:0]` corresponds to channel 1 and `tx_vodctrl [5:3]` corresponds to channel 2).

PMA Control Ports Used in a Read Transaction

The width of the PMA control ports for a read transaction are always separate for each channel as explained in “Method 2: Writing the Same Control Signals to Control All the Transceiver Channels” on page 3-16.

Write Transaction

Because the PMA controls of all the channels are written, if you want to reconfigure a specific channel connected to the `ALTGX_RECONFIG` instance, set the new value at the corresponding PMA control port of the channel under consideration and retain the previously stored values in the other active channels with a read transaction prior to this write transaction.

For example, if the number of channels controlled by the `ALTGX_RECONFIG` instance is two, the `tx_vodctrl` signal in this case would be 6 bits wide. The `tx_vodctrl [2:0]` signal corresponds to channel 1 and the `tx_vodctrl [5:3]` signal corresponds to channel 2.

- To dynamically reconfigure the PMA controls of only channel 2 with a new value, first perform a read transaction to retrieve the existing PMA control values from `tx_vodctrl_out [5:0]`. Use the `tx_vodctrl_out [2:0]` value for `tx_vodctrl [2:0]` to write in channel 1. By doing so, channel 1 is overwritten with the same value.
- Perform a write transaction. This ensures that the new values are written only to channel 2 while channel 1 remains unchanged.

Clocking/Interface Options

The following describes the **Clocking/Interface** options available in Cyclone IV GX devices. The core clocking setup describes the transceiver core clocks that are the write and read clocks of the Transmit Phase Compensation FIFO and the Receive Phase Compensation FIFO, respectively. Core clocking is classified as transmitter core clocking and receiver core clocking.

Table 3–6 lists the supported clocking interface settings for channel reconfiguration mode in Cyclone IV GX devices.

Table 3–6. Dynamic Reconfiguration Clocking Interface Settings in Channel Reconfiguration Mode

ALTGX Setting	Description
Dynamic Reconfiguration Channel Internal and Interface Settings	
How should the receivers be clocked?	Select one of the available options: <ul style="list-style-type: none"> ■ Share a single transmitter core clock between receivers ■ Use the respective channel transmitter core clocks ■ Use the respective channel receiver core clocks
How should the transmitters be clocked?	Select one of the available options: <ul style="list-style-type: none"> ■ Share a single transmitter core clock between transmitters ■ Use the respective channel transmitter core clocks

Transmitter core clocking refers to the clock that is used to write the parallel data from the FPGA fabric into the Transmit Phase Compensation FIFO. You can use one of the following clocks to write into the Transmit Phase Compensation FIFO:

- **tx_coreclk**—you can use a clock of the same frequency as tx_clkout from the FPGA fabric to provide the write clock to the Transmit Phase Compensation FIFO. If you use tx_coreclk, it overrides the tx_clkout options in the ALTGX MegaWizard Plug-In Manager.
- **tx_clkout**—the Quartus II software automatically routes tx_clkout to the FPGA fabric and back into the Transmit Phase Compensation FIFO.

Table 1-31. RSDS Transmitter Timing Specifications for Cyclone IV Devices ^{(1), (2), (4)} (Part 2 of 2)

Symbol	Modes	C6			C7, I7			C8, A7			C8L, I8L			C9L			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
t _{LOCK} ⁽³⁾	—	—	—	1	—	—	1	—	—	1	—	—	1	—	—	1	ms

Notes to Table 1-31:

- (1) Applicable for true RSDS and emulated RSDS_E_3R transmitter.
- (2) Cyclone IV E devices—true RSDS transmitter is only supported at the output pin of Row I/O Banks 1, 2, 5, and 6. Emulated RSDS transmitter is supported at the output pin of all I/O Banks.
Cyclone IV GX devices—true RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.
- (3) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.
- (4) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Table 1-32. Emulated RSDS_E_1R Transmitter Timing Specifications for Cyclone IV Devices ^{(1), (3)} (Part 1 of 2)

Symbol	Modes	C6			C7, I7			C8, A7			C8L, I8L			C9L			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f _{HCLK} (input clock frequency)	×10	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×8	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×7	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×4	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×2	5	—	85	5	—	85	5	—	85	5	—	85	5	—	72.5	MHz
	×1	5	—	170	5	—	170	5	—	170	5	—	170	5	—	145	MHz
Device operation in Mbps	×10	100	—	170	100	—	170	100	—	170	100	—	170	100	—	145	Mbps
	×8	80	—	170	80	—	170	80	—	170	80	—	170	80	—	145	Mbps
	×7	70	—	170	70	—	170	70	—	170	70	—	170	70	—	145	Mbps
	×4	40	—	170	40	—	170	40	—	170	40	—	170	40	—	145	Mbps
	×2	20	—	170	20	—	170	20	—	170	20	—	170	20	—	145	Mbps
	×1	10	—	170	10	—	170	10	—	170	10	—	170	10	—	145	Mbps
t _{DUTY}	—	45	—	55	45	—	55	45	—	55	45	—	55	45	—	55	%
TCCS	—	—	—	200	—	—	200	—	—	200	—	—	200	—	—	200	ps
Output jitter (peak to peak)	—	—	—	500	—	—	500	—	—	550	—	—	600	—	—	700	ps
t _{RISE}	20 – 80%, C _{LOAD} = 5 pF	—	500	—	—	500	—	—	500	—	—	500	—	—	500	—	ps
t _{FALL}	20 – 80%, C _{LOAD} = 5 pF	—	500	—	—	500	—	—	500	—	—	500	—	—	500	—	ps